IN THE SPECIFICATION:

Please replace paragraph number **[0002]** with the following rewritten paragraph:

[0002] State of the Art: Conventional quad flat packages (QFP) are formed with a semiconductor die connected to a lead frame and being encapsulated to form a package such that a plurality of leads extends laterally outwardly from each side of the periphery of the encapsulating structure. Such a configuration is relatively simple in design and may be efficiently produced. However, the QFP-type semiconductor has shown various design and production limitations. For example, reducing the overall package size of a QFP becomes difficult because of the arrangement of leads about the lateral periphery of the package. This is particularly evident when reduced package size is attempted to be combined with increasing the number of input/output ~~(I/0)~~ (I/O) connections required for the smaller yet ever-more complex dice representing the state of the art.